## HI0805O121R-10

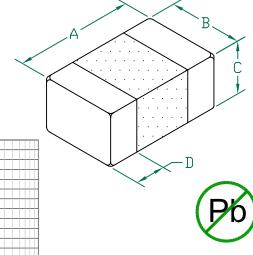
## UNCONTROLLED DOCUMENT

## PHYSICAL DIMENSIONS:

A  $2.00 [.079] \pm 0.20 [.008]$ 

B 1.25 [.049] ± 0.20 [.008]

C 0.90 [.035] ± 0.20 [.008]



ELECTRICAL CHARACTERISTICS:											
Z @ 100M ( Ω )		DCR $\left(\begin{array}{c}\Omega\end{array}\right)$	Rated Current								
Nominal	120										
Minimum	nimum 90										
Maximum	150	0.020	3500 mA								

NOTES: UNLESS OTHERWISE SPECIFIED

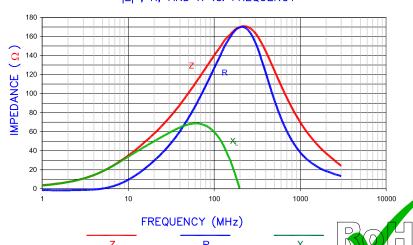
- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPER.
- 2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 3. TERMINATION FINISH IS 100% TIN.

# 180 160 140 140 120 100 100 100 1000 1000

Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS

## FREQUENCY (MHz)

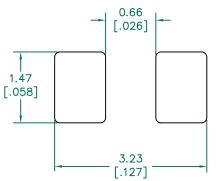
## |Z| , R, AND X vs. FREQUENCY



AGILENT E4991A RF Impedance/Material Analyzer

HP 16194A Test Fixture REF, 5522

## LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [.030] to this dimension.)

## REFLOW SOLDERING 250 PRE-HEATING SOLDERING [482] [482] [250 PRE-HEATING SOLDERING COOLING [482] [482] [482] [482] [482] [482]

RECOMMENDED SOLDERING CONDITIONS

100 SECONDS 5 - 10 SECONDS 60 SECONDS

DIMENSIONS ARE IN mm [INCHES].			This print is the property of Lair	d							
				Tech. and is loaned in confidence subject to return upon request and							
				with the understanding that no		<b>Laird</b>					
				written consent of Laird Tech. All rights to design or invention are							
В	CHANGE TO PAPER TAPE	03/04/10	JUN	reserved. PROJECT/PART NUMBER:	ᆚ						
D	UPDATE COMPANY LOGO & ROHS SYMBOL	06/01/09	JRK	l '	RE	:v	PART TY		DRAWN BY:		
С	UPDATE COMPANY LOGO	01/16/08	JRK	HI08050121R-10		E CO		-FIRE JRK			
В	UPDATE CURVES	03/29/06	JRK	DATE: 08/23/04	SCALE: NTS		70	SHEET:			
Α	ORIGINAL DRAFT	08/23/04	JRK	CAD #			_				
REV	DESCRIPTION	DATE	INT	"HI08050121R-10-E			2	of 2			